

Kamila Piotrowska

List of Publications by Year in descending order

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Version: 2024-02-01

17
papers

199
citations

1162367

8
h-index

1125271

13
g-index

17
all docs

17
docs citations

17
times ranked

85
citing authors

#	ARTICLE	IF	CITATIONS
1	Importance of PCBA cleanliness in humidity interaction with electronics. , 2022, , 141-196.		1
2	Factors determining water film buildup on surfaces and relevance to corrosion in electronics. , 2022, , 93-140.		0
3	Materials and processes for electronic devices and components: how they contribute to corrosion reliability?. , 2022, , 197-250.		0
4	Corrosion reliability testing, standards, and failure analysis. , 2022, , 339-380.		0
5	Alkanolamines as activators in no-clean flux systems: investigation of humidity robustness and solderability. Journal of Materials Science: Materials in Electronics, 2021, 32, 4961-4981.	1.1	6
6	Investigation on the Hygroscopicity of Deposits at the Cold-End of Biomass and Coal-Fired Plants. Energy & Fuels, 2021, 35, 8006-8022.	2.5	1
7	Transformation of reflow solder flux residue under humid conditions. Microelectronics Reliability, 2021, 123, 114195.	0.9	5
8	Humidity Robustness of Plasma-Coated PCBs. Journal of Electronic Materials, 2020, 49, 848-860.	1.0	3
9	Residue-Assisted Water Layer Build-Up Under Transient Climatic Conditions and Failure Occurrences in Electronics. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1617-1635.	1.4	16
10	Thermal decomposition of binary mixtures of organic activators used in no-clean fluxes and impact on PCBA corrosion reliability. Soldering and Surface Mount Technology, 2019, 32, 93-103.	0.9	10
11	No-Clean Solder Flux Chemistry and Temperature Effects on Humidity-Related Reliability of Electronics. Journal of Electronic Materials, 2019, 48, 1207-1222.	1.0	25
12	Effect of Solder Mask Surface Chemistry and Morphology on the Water Layer Formation Under Humid Conditions. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1756-1768.	1.4	16
13	Introduction of axial chirality at a spiro carbon atom in the synthesis of pentaerythritolâ€‘imine macrocycles. Organic and Biomolecular Chemistry, 2018, 16, 981-987.	1.5	7
14	Parametric Study of Solder Flux Hygroscopicity: Impact of Weak Organic Acids on Water Layer Formation and Corrosion of Electronics. Journal of Electronic Materials, 2018, 47, 4190-4207.	1.0	41
15	Humidity-related failures in electronics: effect of binary mixtures of weak organic acid activators. Journal of Materials Science: Materials in Electronics, 2018, 29, 17834-17852.	1.1	26
16	Thermal decomposition of solder flux activators under simulated wave soldering conditions. Soldering and Surface Mount Technology, 2017, 29, 133-143.	0.9	27
17	Steam assisted oxide growth on aluminium alloys using oxidative chemistries: Part I Microstructural investigation. Applied Surface Science, 2015, 355, 820-831.	3.1	15